

Customer No.: 31561
Application No.: 10/064,426
Docket No.: 7983-US-PA

In the abstract

[0026] A layout structure of a central processing unit (CPU) that supports two different package techniques, ~~[comprising]~~having a motherboard that comprising the layout structure and a layout method. The layout structure of the preferred embodiment according to the present invention from up to down sequentially placed a top signal layer, a grounded layer, a power layer having an operating potential area and a grounded potential area, and a bottom solder layer in the area where the signals of the CPU are coupled to the signals of the control chip, so that the signals that are placed on the bottom solder layer can refer to a grounded potential area of the power layer. ~~[Therefore, part of signals of the CPU that are coupled to the control chip can be placed on the bottom solder layer. Since the preferred embodiment of the present invention provides more flexibility in the placement design, a layout structure that supports the Pentium IV CPUs of different package techniques can be designed on the motherboard of the 4 layers stack structure, and these two CPUs can supported by the same control chip.]~~